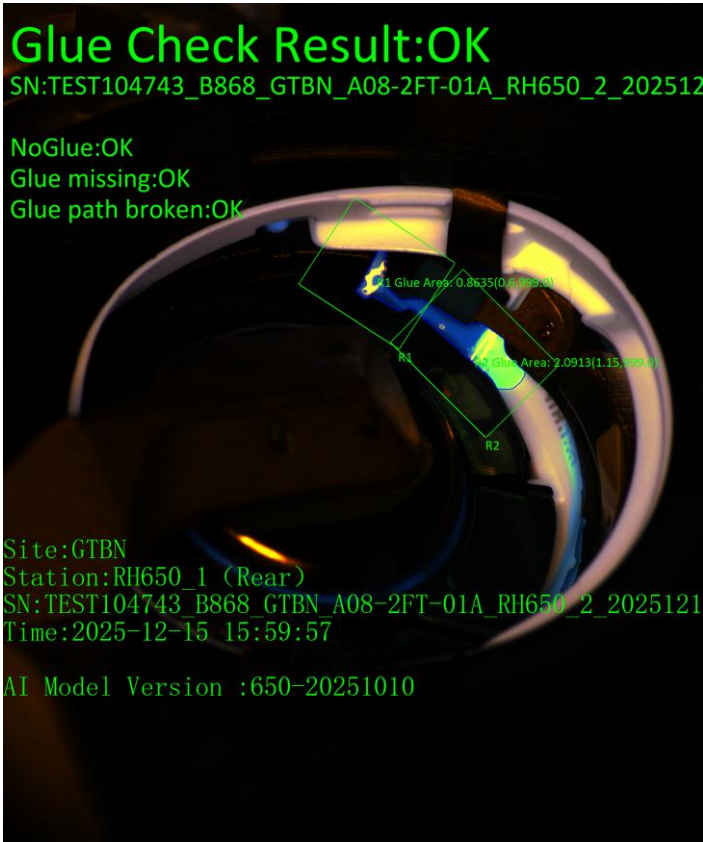
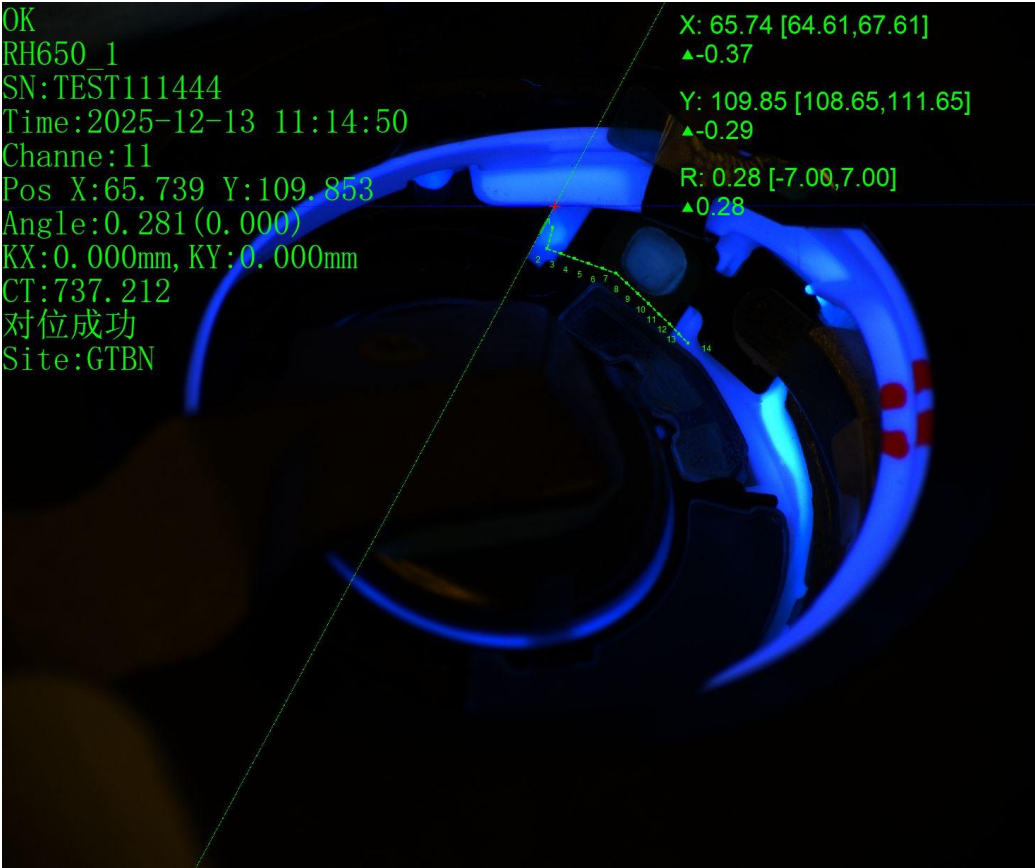


H650

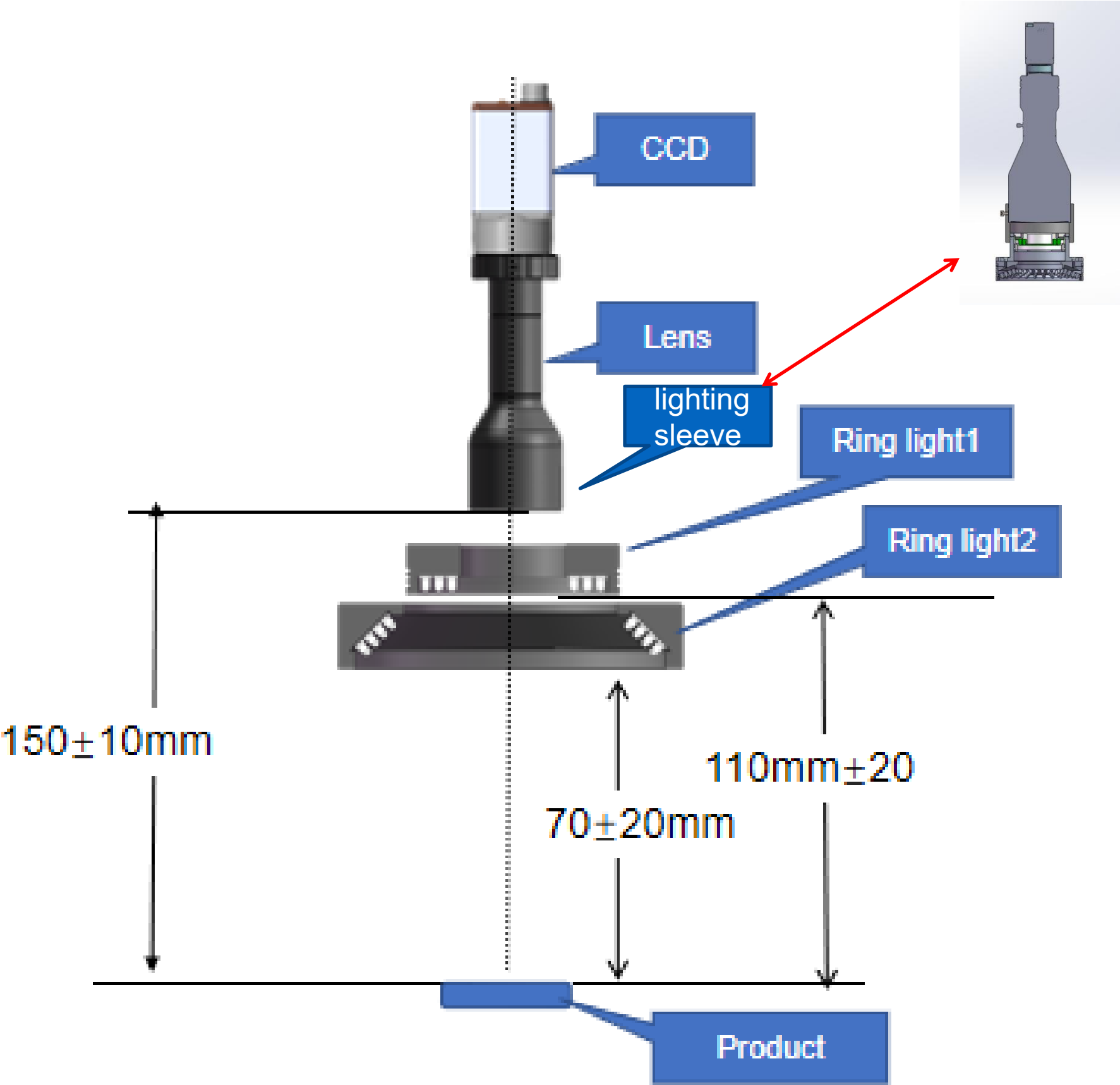
Station ID	Station Description	Vendor	Process Type		MIL
H650		BZ	Dispense		



主程序		删除				单点参数		速度参数		生产模式						
序号	指令类型	X	Y	Z	U	V	参数1	参数2	参数3	参数4	注释	X相对差值	Y相对差值	Z相对差值	U相对差值	V相对差值
1	定位	0	0	0	0	0	速度:300	TwoMark	次数:0							
2	线头	65.785	109.277	0	27	-70	速度:30	Z轴高...	飞行...	延后...	11	0.042	-0.435	0	0	0
3	延时						延时s...									
4	线中	65.896	108.836	0	27	-70	速度:24			延后...	22	0.153	-0.876	0	0	0
5	延时						延时s...									
6	线中	65.612	108.736	0	27	-70	速度:24			延后...	3	-0.131	-0.976	0	0	0
7	线中	65.328	108.637	0	27	-70	速度:24			延后...	4	-0.415	-1.075	0	0	0
8	线中	65.044	108.537	0	27	-70	速度:24			延后...	5	-0.699	-1.175	0	0	0
9	线中	64.76	108.437	0	27	-70	速度:24			延后...	6	-0.983	-1.275	0	0	0
10	线中	64.476	108.338	0	27	-70	速度:24			延后...	77	-1.267	-1.374	0	0	0
11	线中	64.257	108.129	0	27	-70	速度:24			延后...	8	-1.486	-1.583	0	0	0
12	线中	64.038	107.919	0	27	-70	速度:24			延后...	9	-1.705	-1.793	0	0	0
13	线中	63.82	107.71	0	27	-70	速度:24			延后...	10	-1.923	-2.002	0	0	0
14	线中	63.601	107.501	0	27	-70	速度:24			延后...	11	-2.142	-2.211	0	0	0
15	线中	63.382	107.292	0	27	-70	速度:30			延后...	122	-2.361	-2.42	0	0	0
16	延时						延时s...									
17	线中	63.189	107.098	0	27	-70	速度:30			延后...	13	-2.554	-2.614	0	0	0
18	线尾	62.997	106.905	0	27	-70	速度:30	Z轴高...	提前...		144	-2.746	-2.807	0	0	0
19	定位	0	0	0	0	0	速度:300	TwoMark	次数:99							
	结束															

Vision solution description: The CCD takes pictures from top to bottom, locates the product position, guides the machine to dispense, and then rechecks after the dispense is completed.

CCD imaging structure;

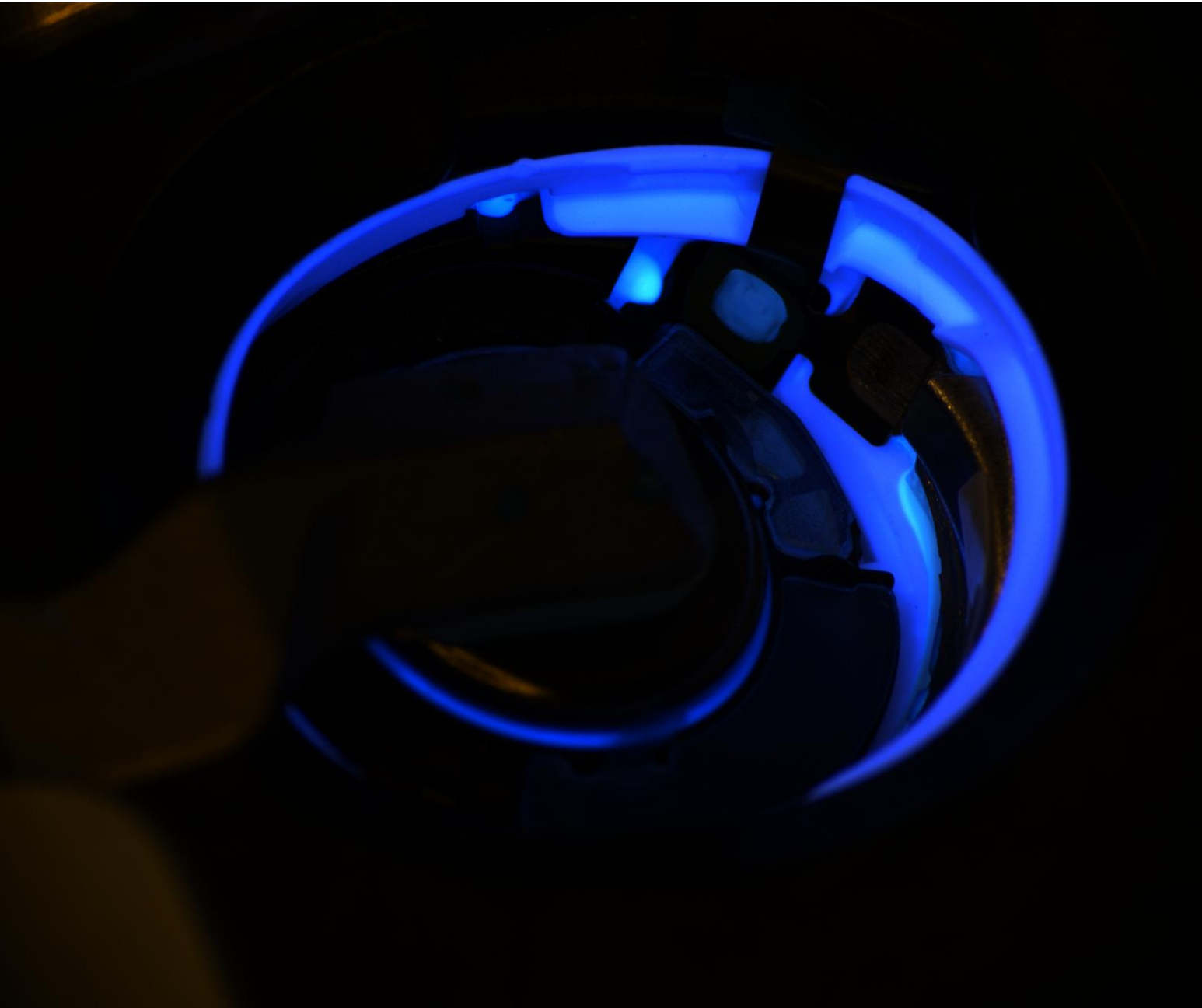


Vision System Diagram

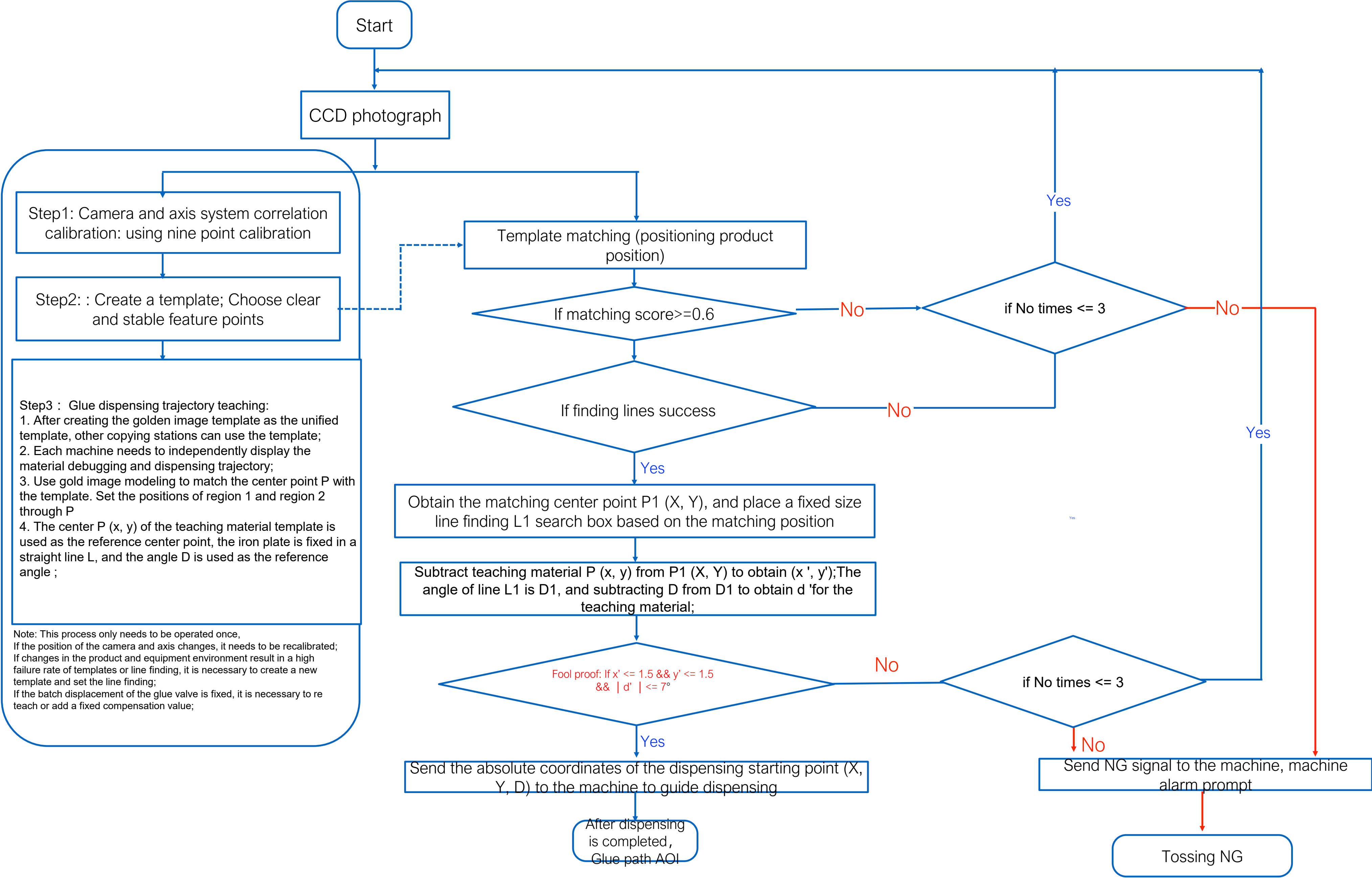
Parameter		
Pixels	FOV	Resolution
2448*2048	21*17.5mm	0.008mm/pixel

BOM(for Dual_station)			
Item	Type	Brand	Quantity
Camera	LY-H500C	Luster	1
Lens	EGXD-RDTD-150-04	Luster	1
Light1	RBM-HRL5390-W	Luster	1
Light2	RBM-HRL9070-UV365-PM	Luster	1
License	VW-VA-SW-GLUE10	Luster	1

Glue path 1  
Golden image1



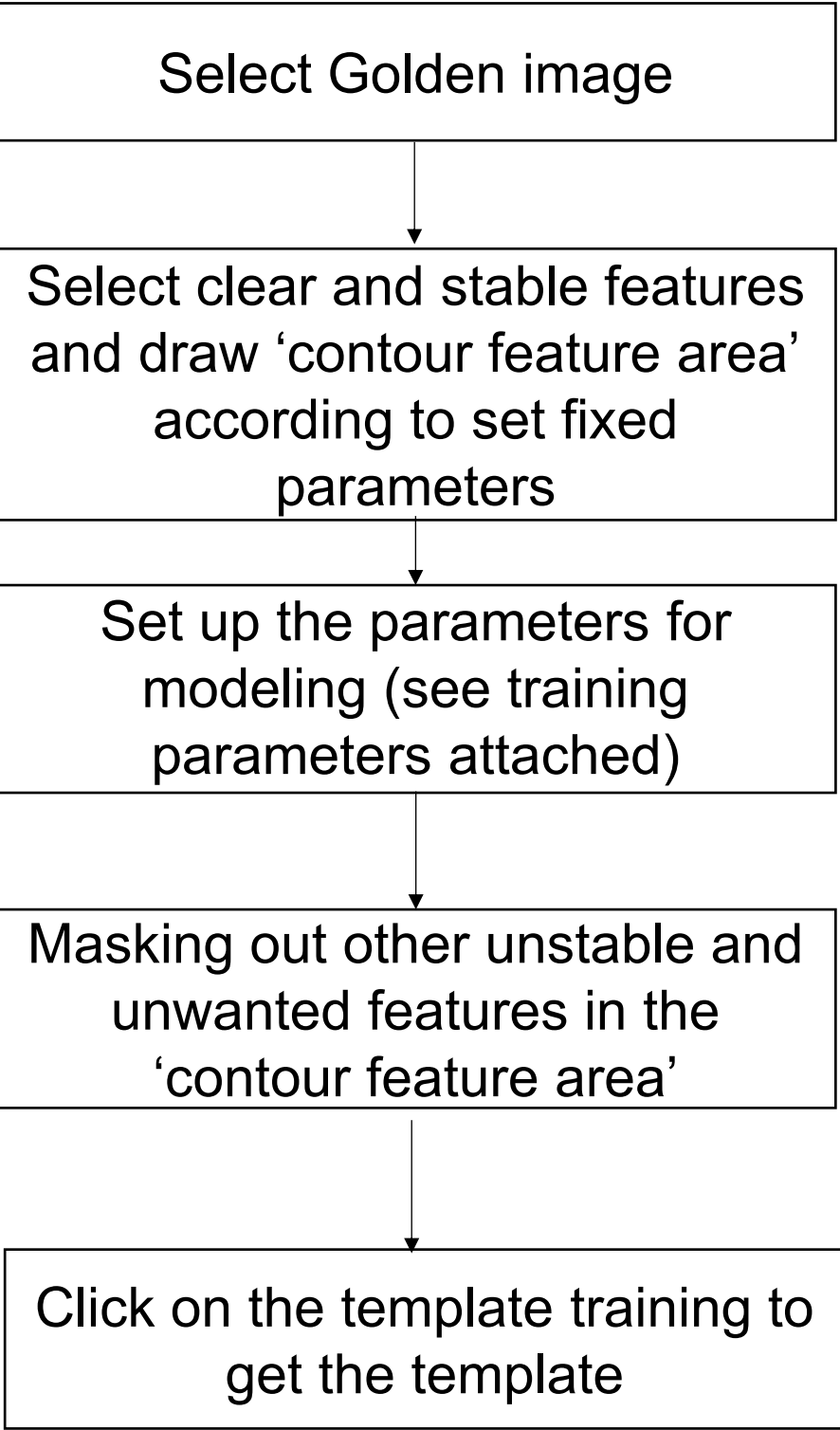
Detailed parameters of golden image1	
Pixel dimension	0.008mm/pixel
CCD resolution	2448*2048
Lens resolution	1000W, 1’
FOV	21*17.5mm
DOV	2.5mm
Lightning Brightness	200
Exposure time	50ms



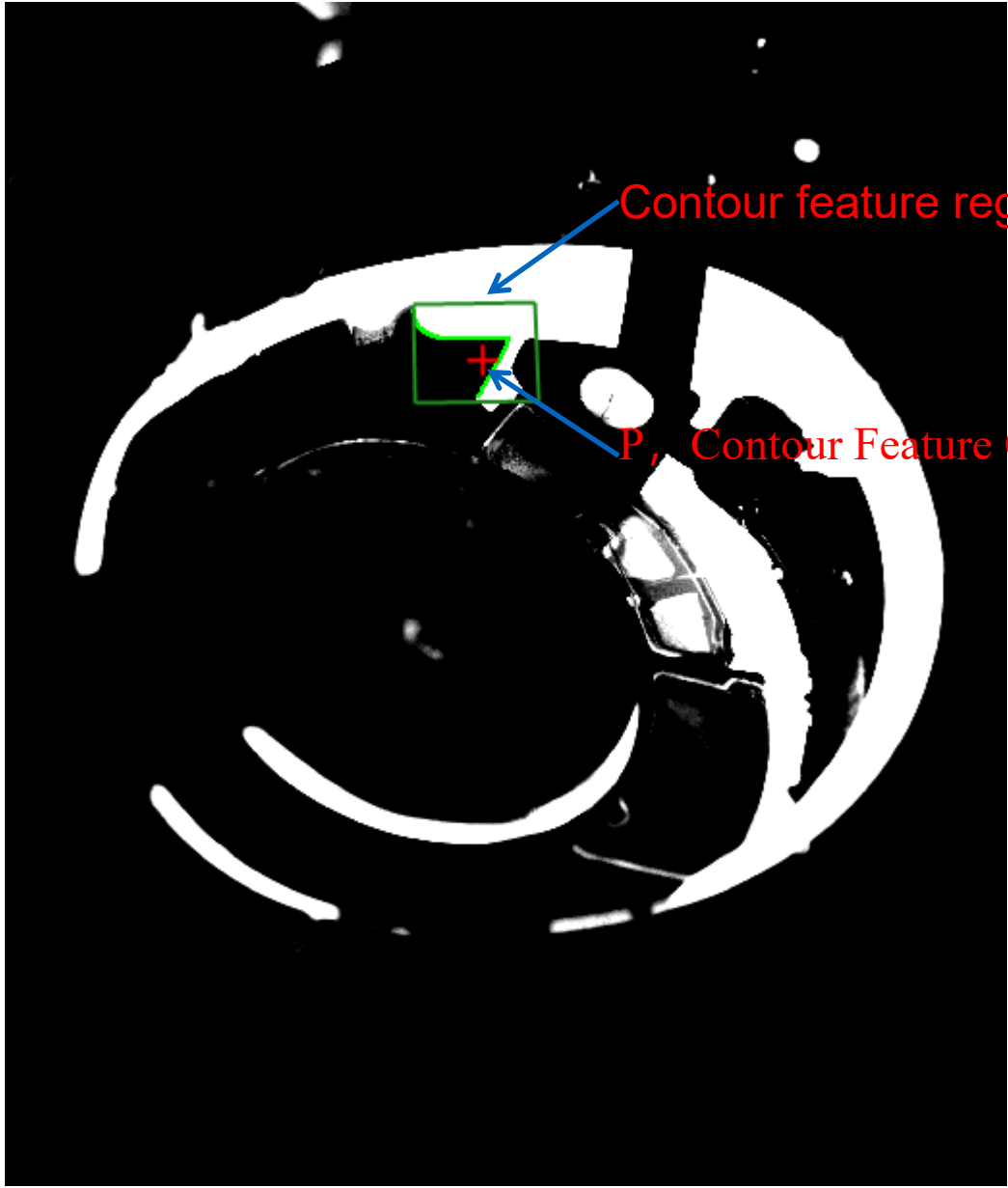
# Pose 1 Vision Workflow

Step	Description	Page	Remark
1	Creating coarse finder templates Pose1	8	
2	Pattern Matching in Pose1	9	
3	Finding lines	10	
4	Curve finding details	10	
6	Glue path AOI Product Glue Path Edge	14	
7	Glue path AOI Glue Area Region	15	
8	FOF	17	





Modeling Process



Template

参数		
<input checked="" type="checkbox"/>	金字塔层数	层数: 4
<input checked="" type="checkbox"/>	自动噪声	噪声阈值: 10
<input checked="" type="checkbox"/>	自动边缘强度	边缘强度阈值: 13437

显示图形控件	
矩形参数	
原点 X:	807.885
原点 Y:	189.832
宽度:	594.439
高度:	650.101
面积:	386445.7
<input type="button" value="确定"/> <input type="button" value="取消"/>	

Training parameters

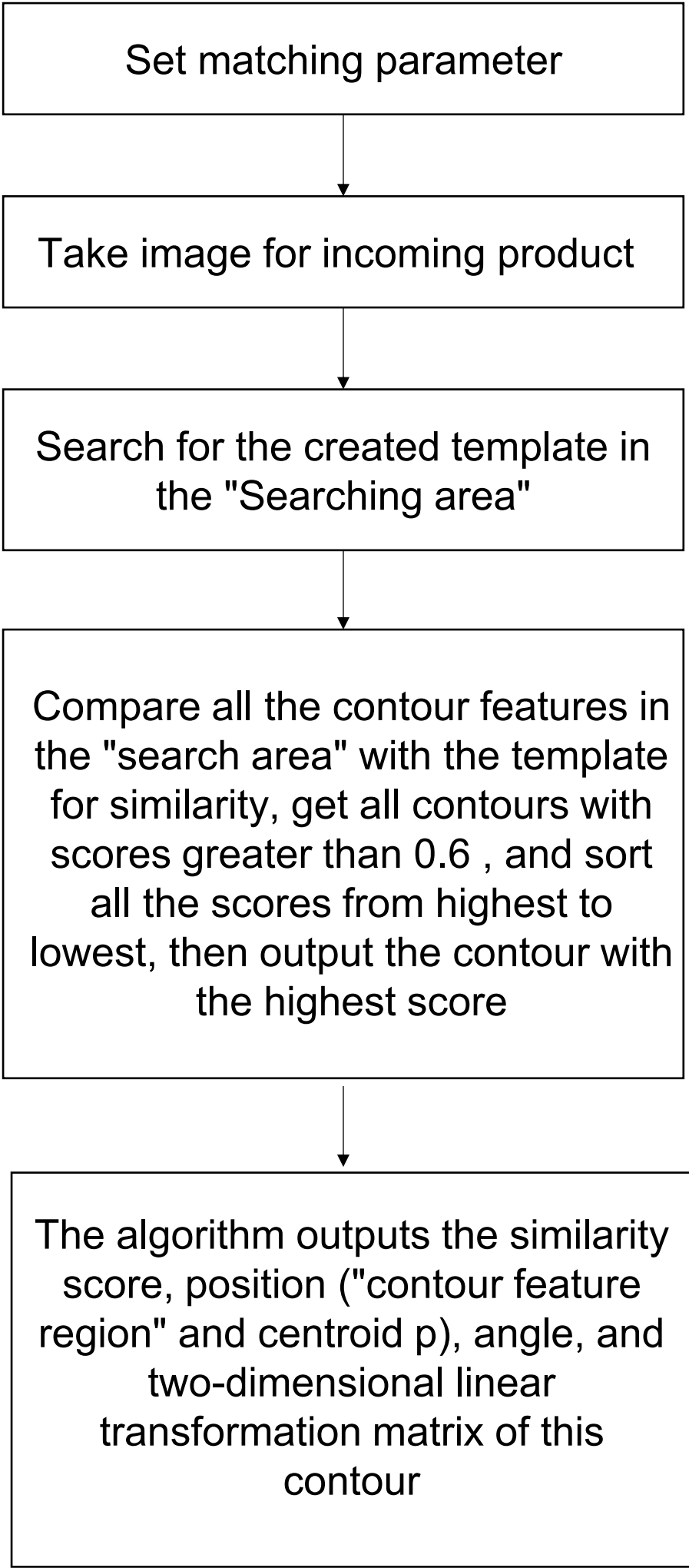
- Modeling feature requirements :
- 1. Stable and clear outline edge, no dirty
  - 2. Do not have multi-layer, complex contours
  - 3. Search area, do not have a close shape of the edge of the contour

When modeling, make good use of the masking function to mask out the unwanted edge contour features. Leaving only stable and clear contour features

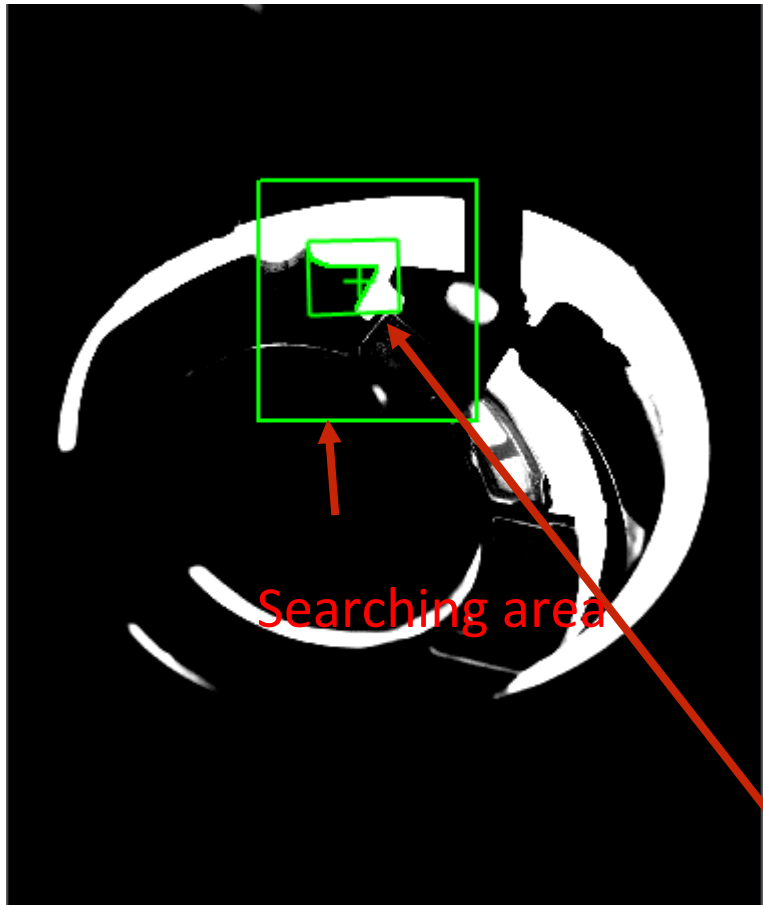
After the modeling is completed, need offline test with all the previous material images to confirm the compatibility of this template for all incoming materials.

Subsequent parameter changes need to be synchronized and updated to all other machines in this station.





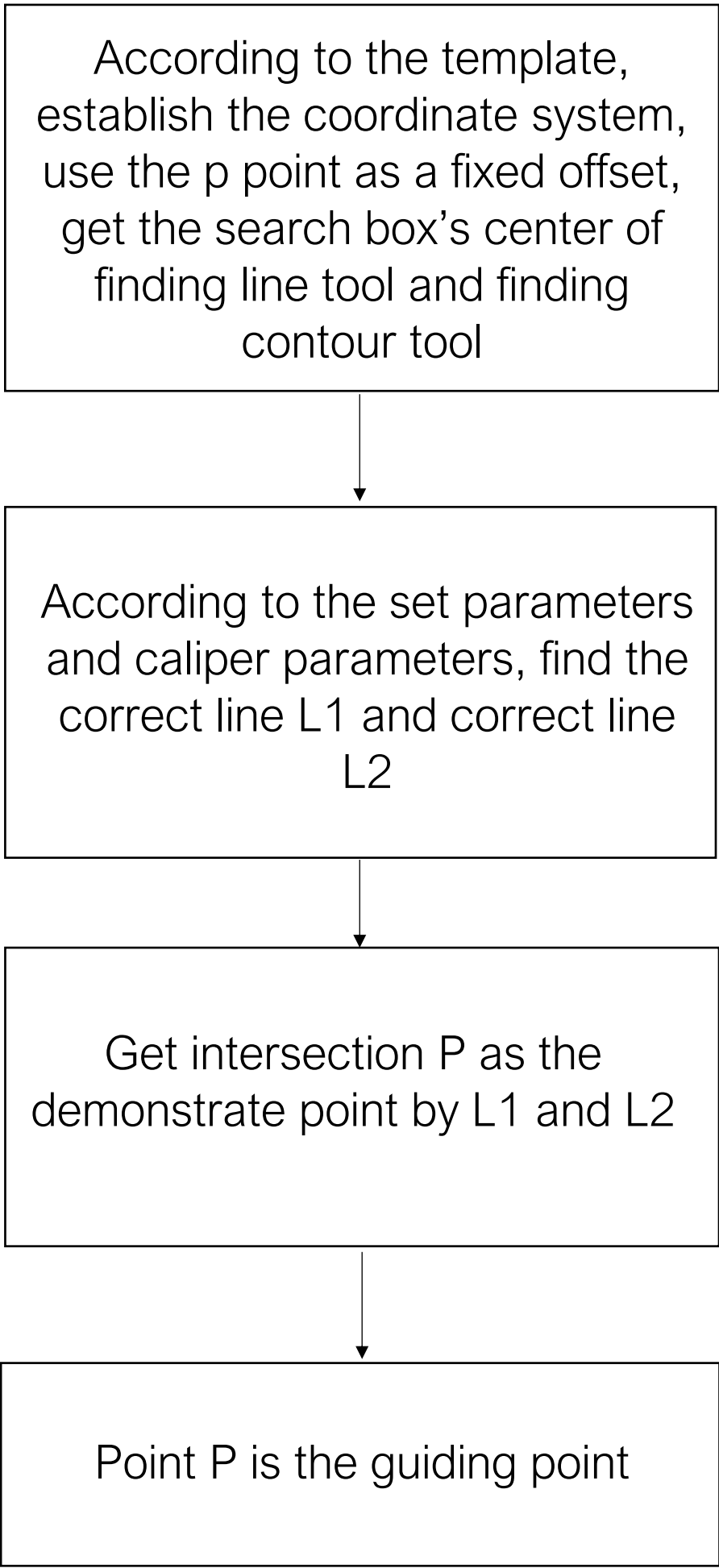
Matching process



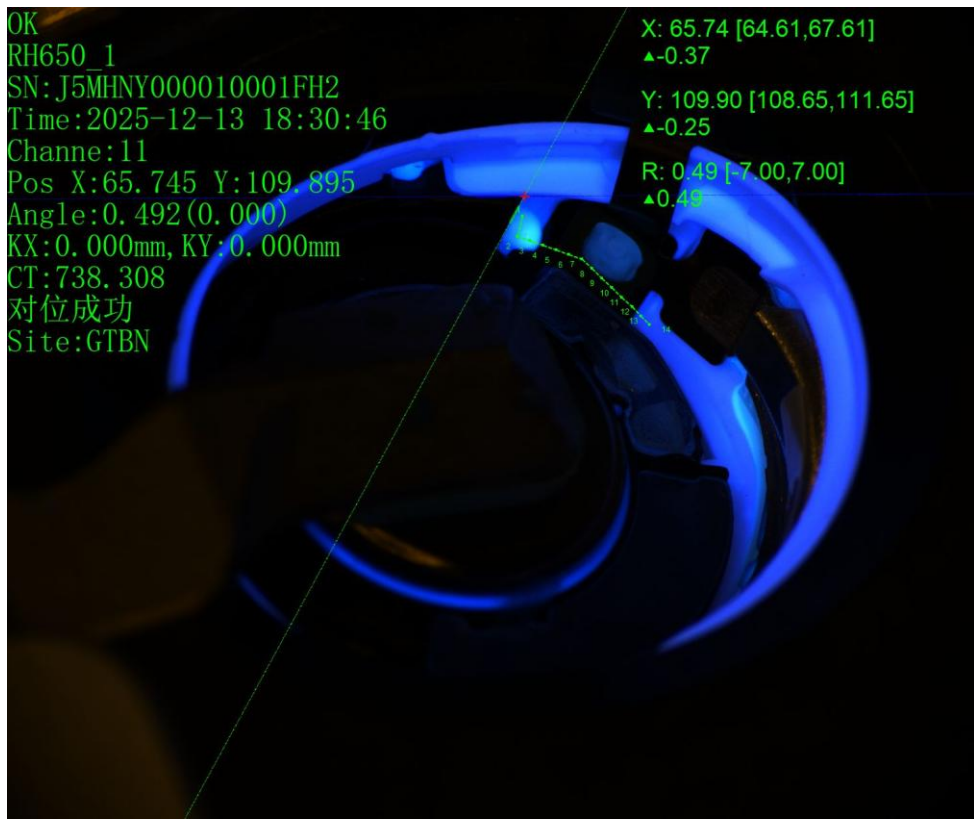
Actual Materials

属性	
ParameterList	
接受阈值	0.600000
对比度阈值	10.000000
重叠比例阈值	0.800000
贪婪度	0.900000
搜索个数	1
是否开启全图	否
搜索区域	680.886384,
是否外部输入	否
搜索模式	高精
开启支持边界	否
任意极性	否
自动金字塔	否
搜索最低金	1
搜索最高金	4
搜索最低角	-15.000000
搜索最高角	15.000000
搜索最低缩	0.980000
搜索最高缩	1.020000

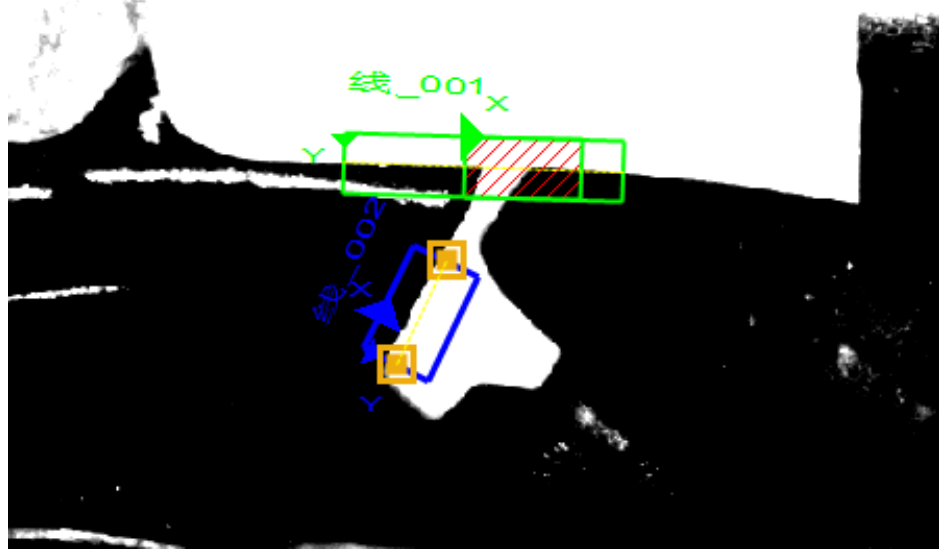
Matching parameter



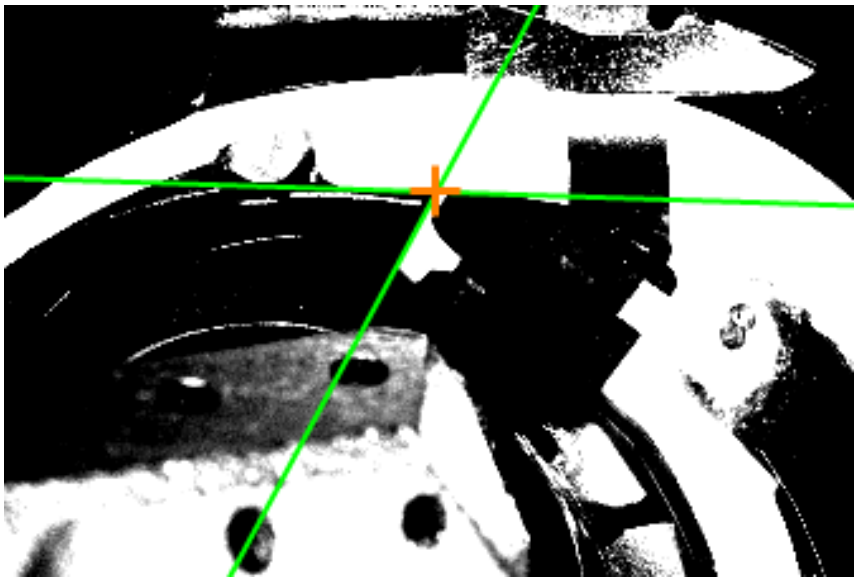
Point demonstration process



Actual Materials

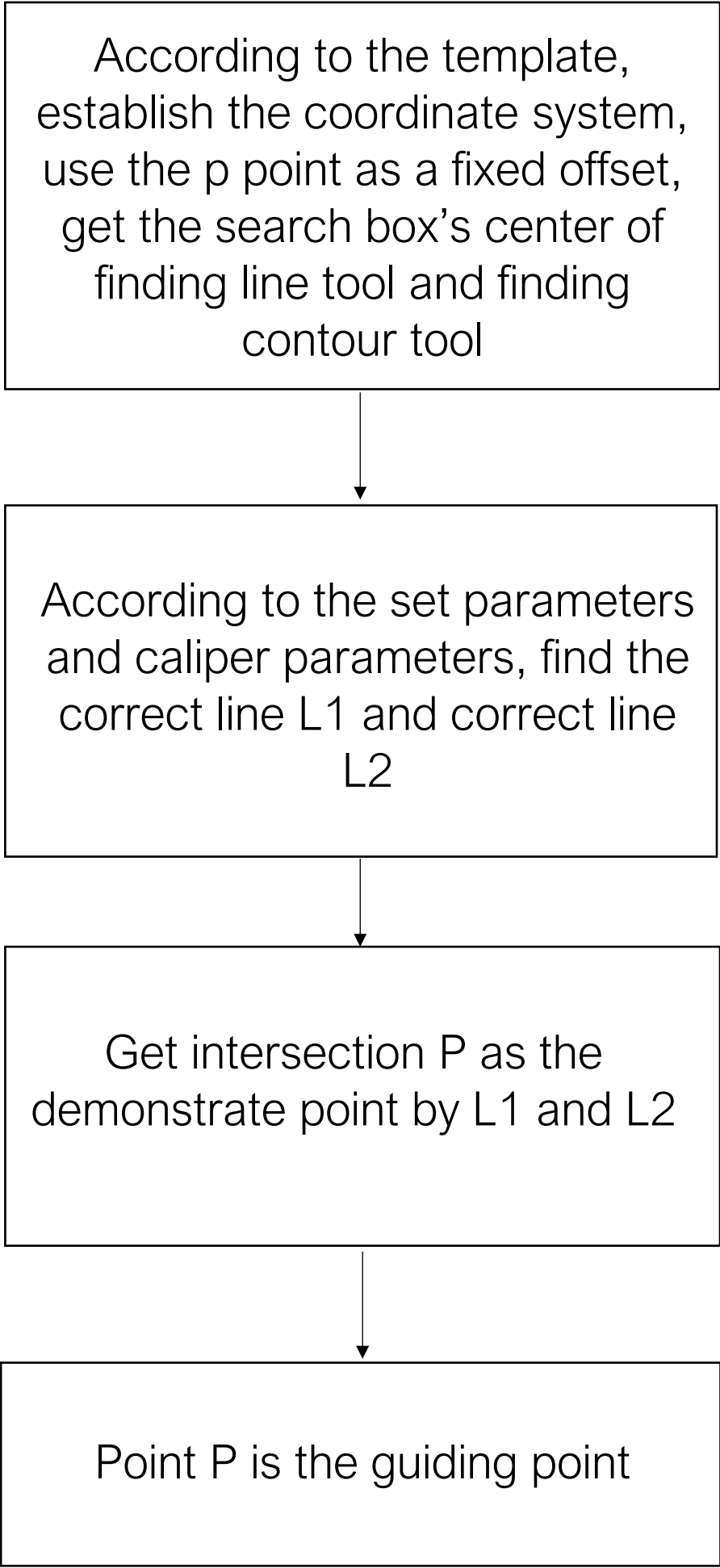


L1 Caliper parameters

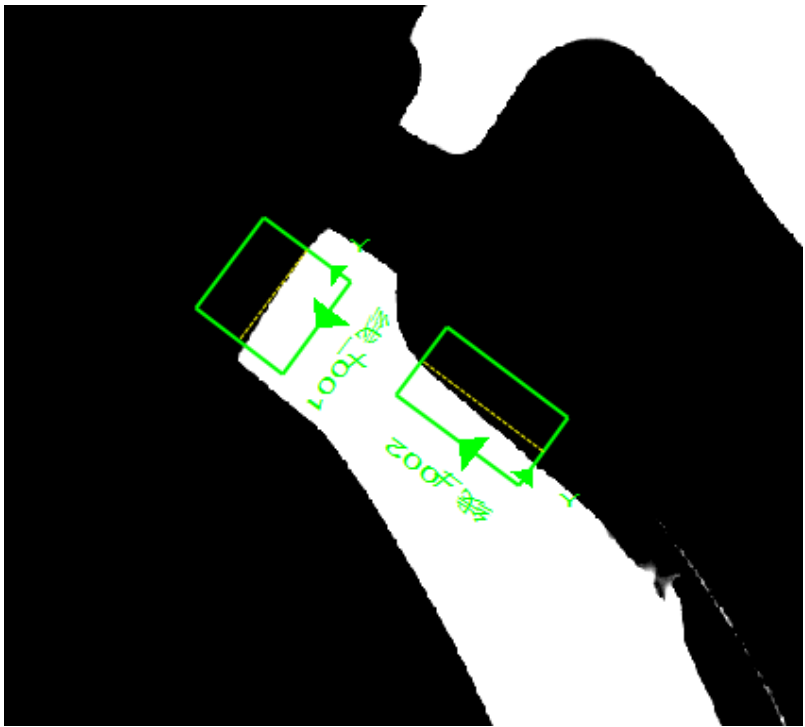


L2 Caliper parameters

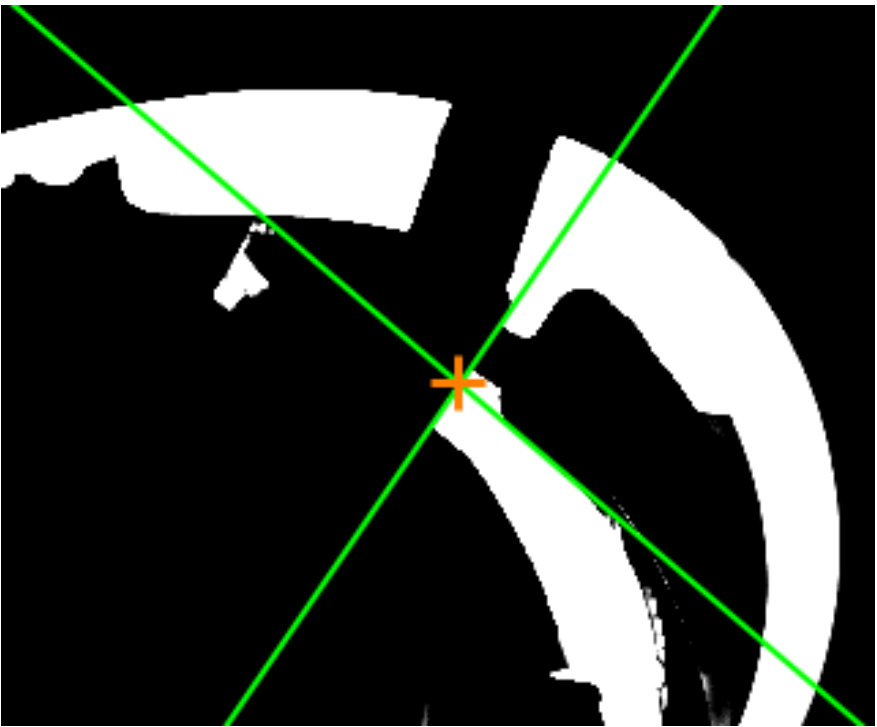
- Incoming material requirements:
1. to ensure that the difference between the material and the modeled material can not be too large (visual inspection can not have obvious differences in the structure)
  2. dirty, foreign matter also can not have a lot, can not obscure the modeled features;



Point demonstration process



L1 Caliper parameters



L2 Caliper parameters

- Incoming material requirements:
- 1. to ensure that the difference between the material and the modeled material can not be too large (visual inspection can not have obvious differences in the structure)
  - 2. dirty, foreign matter also can not have a lot, can not obscure the modeled features;

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# Glue Path AOI MSOP

The algorithm, inspection definition and spec of the glue path AOI.



# H650 | Glue path AOI Product Glue Path Edge

## No Glue

The areas of the glue > 0mm²

## Glue Coverage-Shift

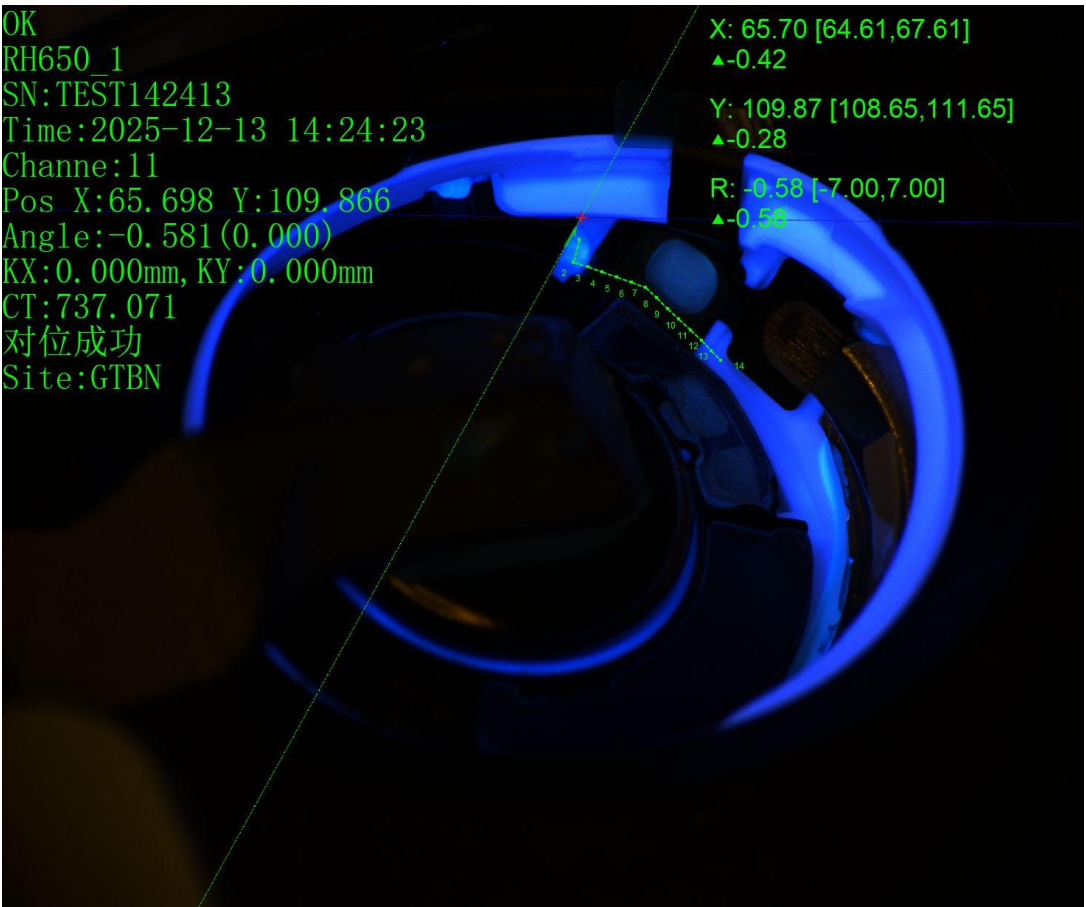
The R1 coverage line should be >= 80% covered by glue path

## Glue Missing

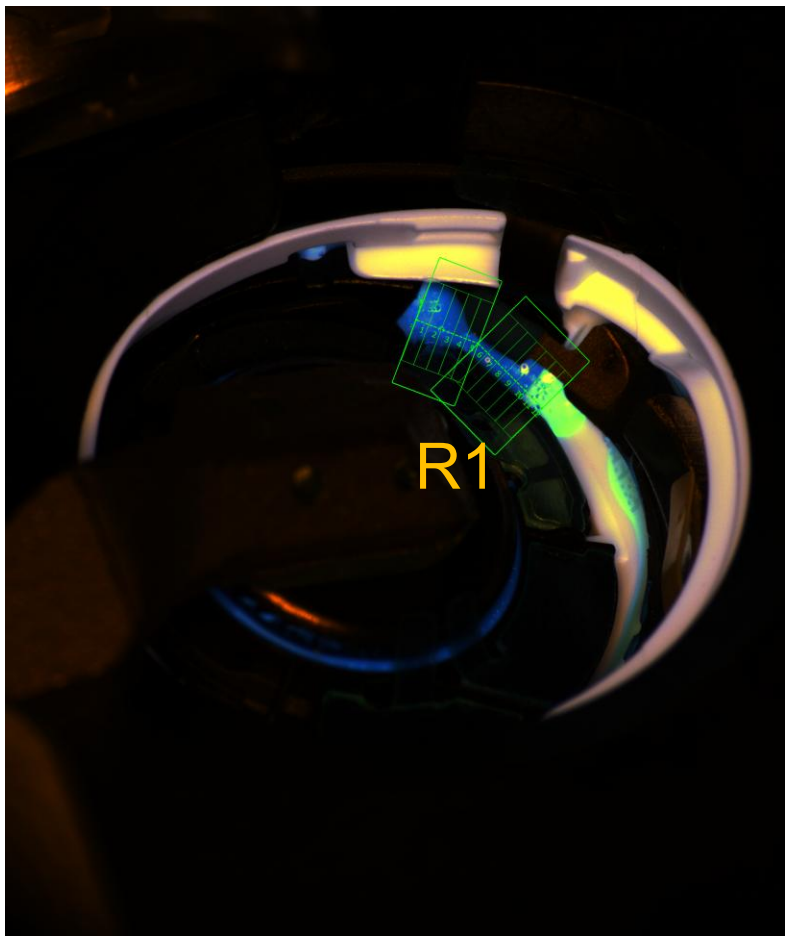
## Glue Broken

The gap of glue breakage ≤ 0.1 mm

Pre-dispense image



Post-dispense image



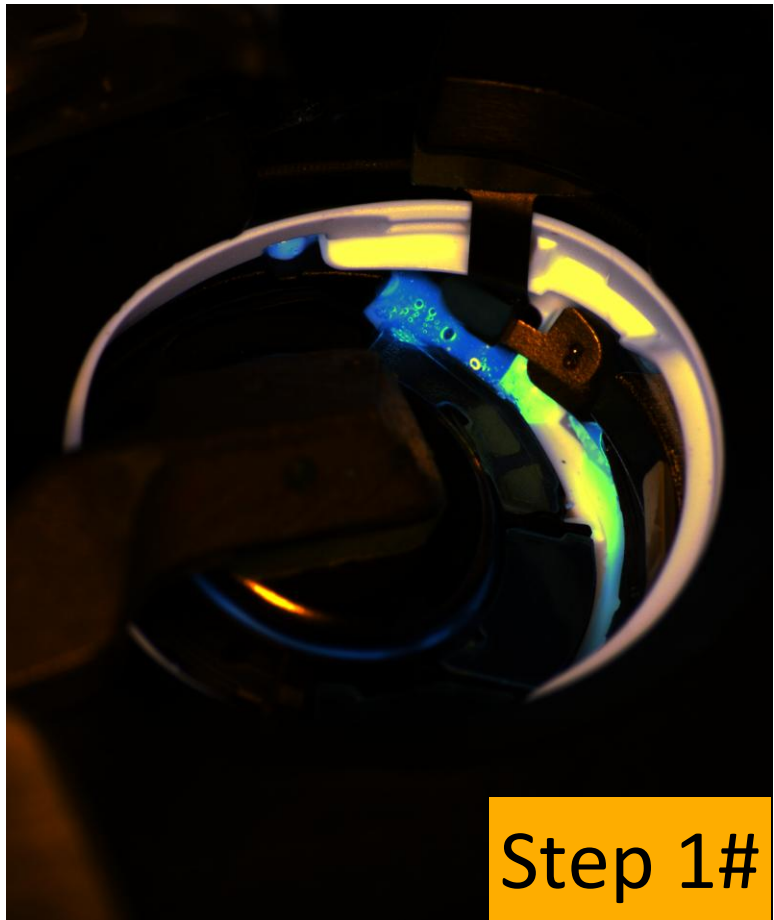
Legend:

- Glue Path Edge
- Glue Coverage Line
- Glue Area Region
- Keep out zone

Pix accuracy:0.0086mm/pix

Region	No Glue	Glue Coverage-Shift	Glue Missing-Area	Glue Broken
R1	Glue area > 0mm²	≥80%	Glue area > 0.6mm²	≤0.1mm

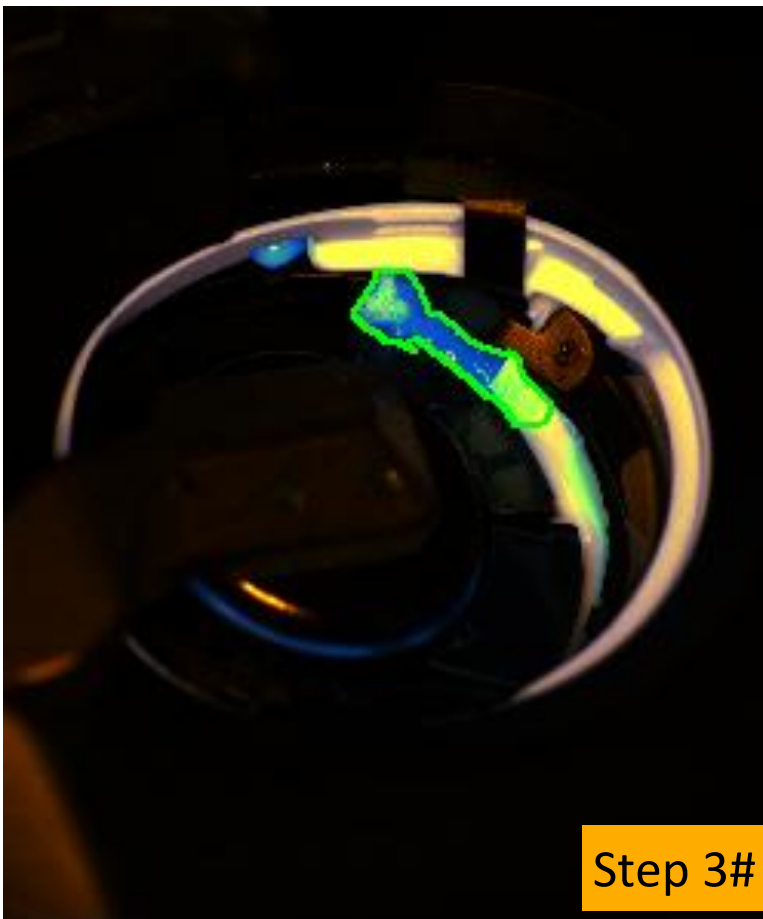
Region	No Glue	Glue Coverage-Shift	Glue Missing-Area	Glue Broken
R2	Glue area > 0mm²	≥80%	Glue area > 1.12mm²	≤0.1mm



Source image (post-dispense)



extract glue color



extract result

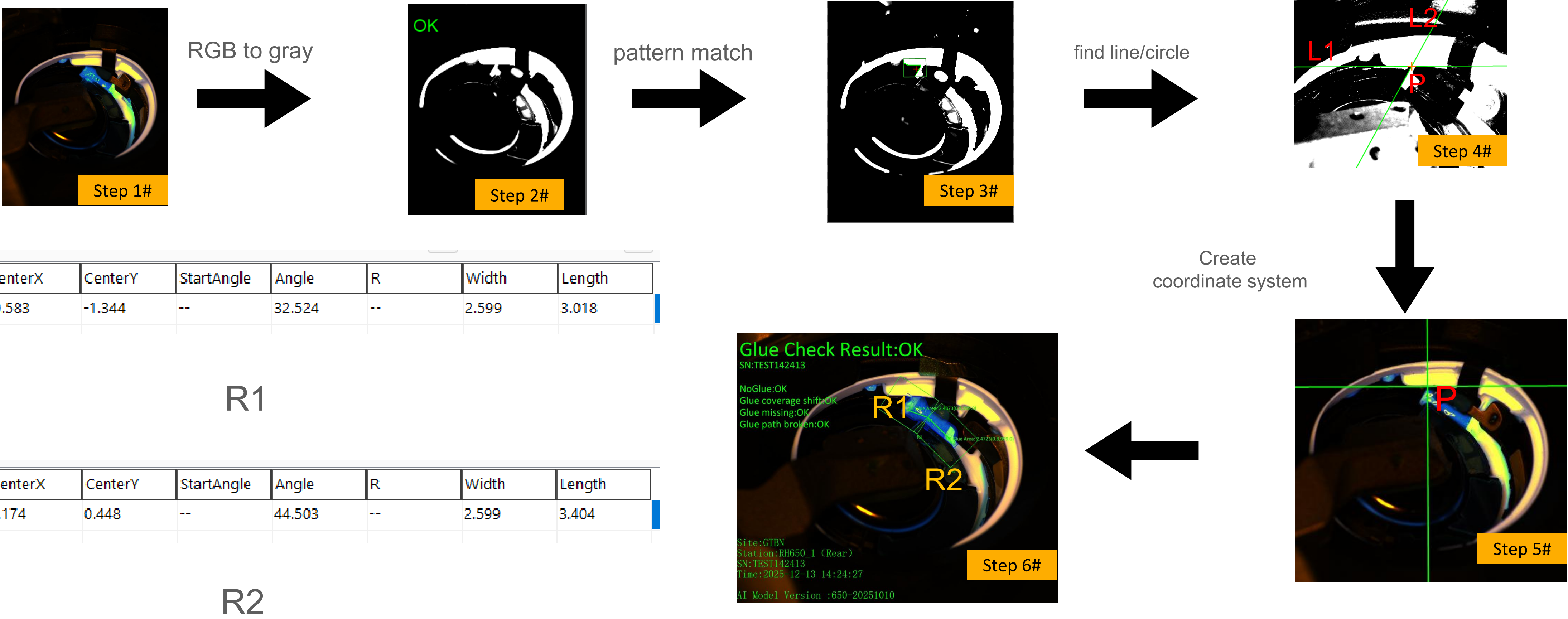
missing
Step 2#

The purpose of this process is used to extract the Glue path

- Step 1# Capture pose1 source image
- Step 2# Extract the color of glue path
- Step 3# Inspect the glue path

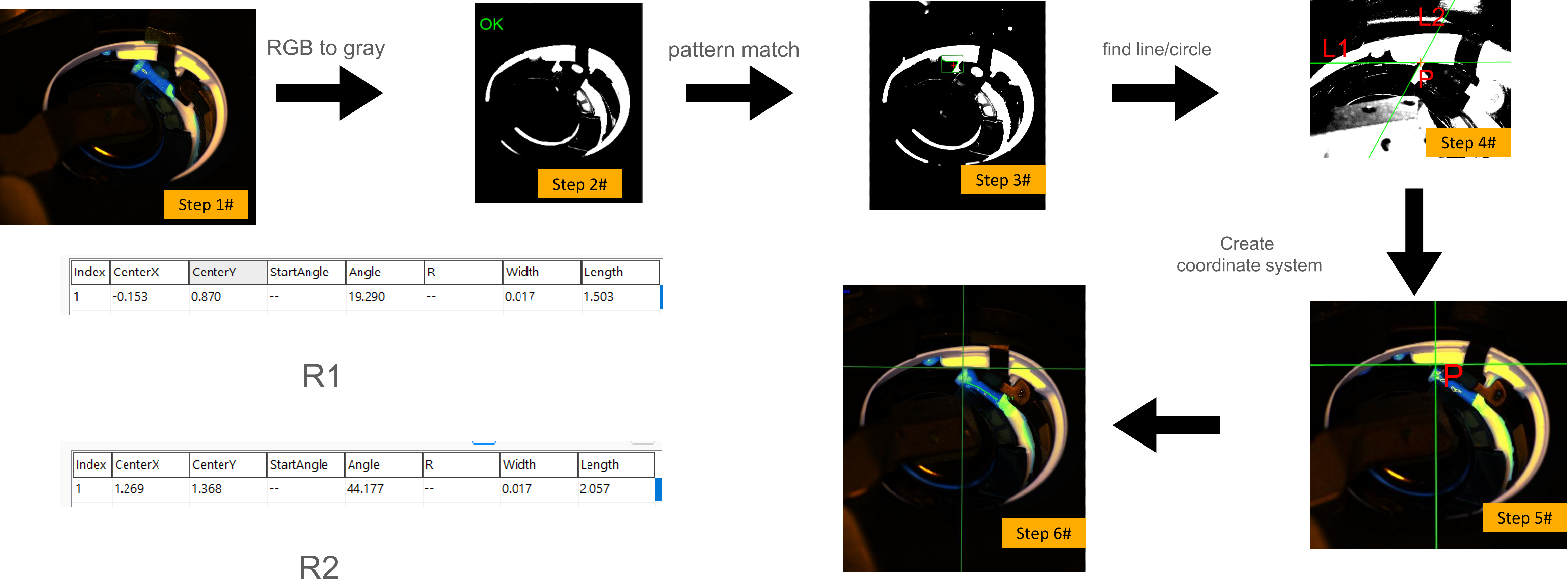


Audio | Glue path AOI Glue Area Region



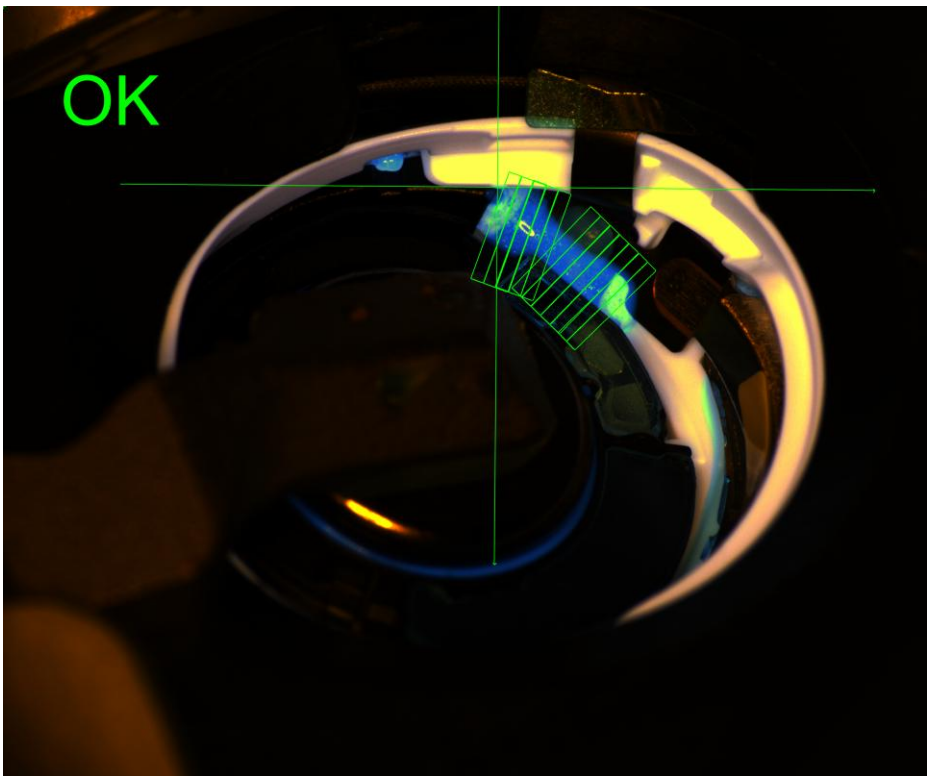
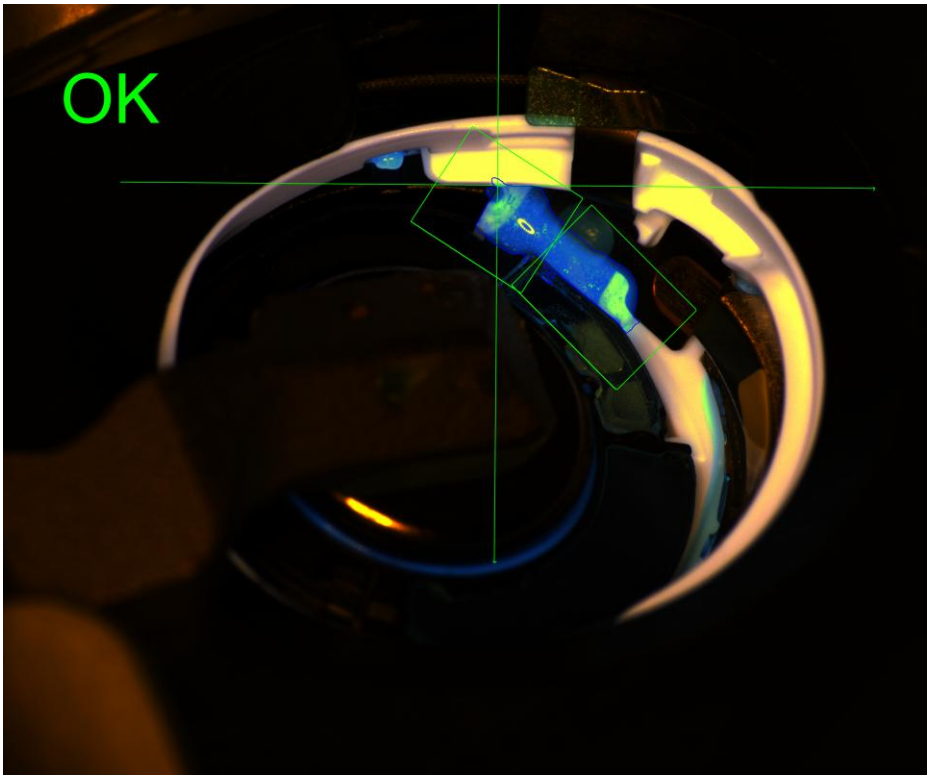
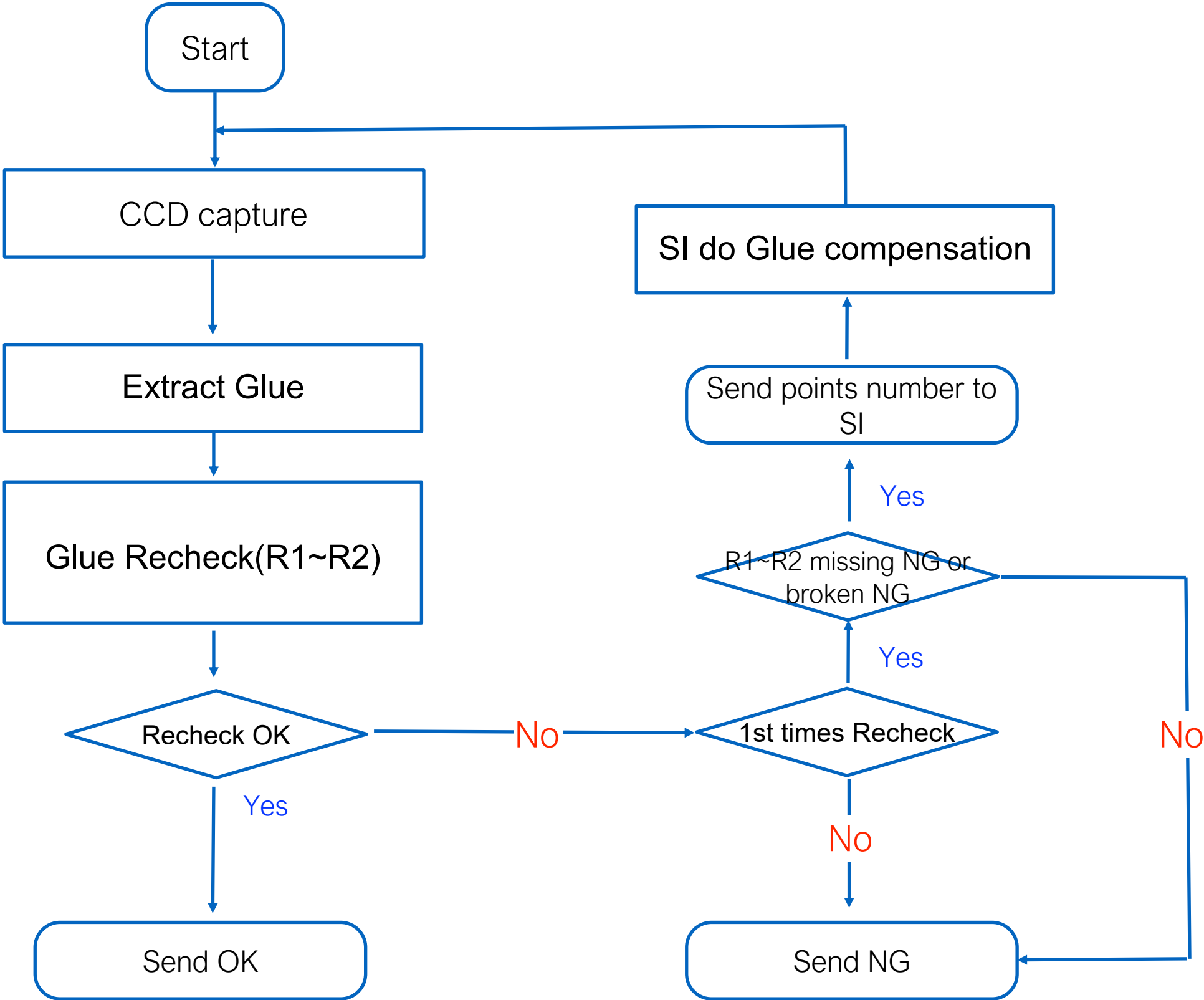
The purpose of this process is used to find the position for dispense and region for coverage inspection:

- Step 1# Capture pos1 source image
- Step 2# RGB image to gray image
- Step 3# Pattern match to get the place of the product
- Step 4# Grab the product characteristics of line to obtain L1&L2, P is intersection point of L1&L2
- Step 5# Establish a product coordinate system by using P and golden line
- Step 6# Place the glue inspection region according to product coordinate system



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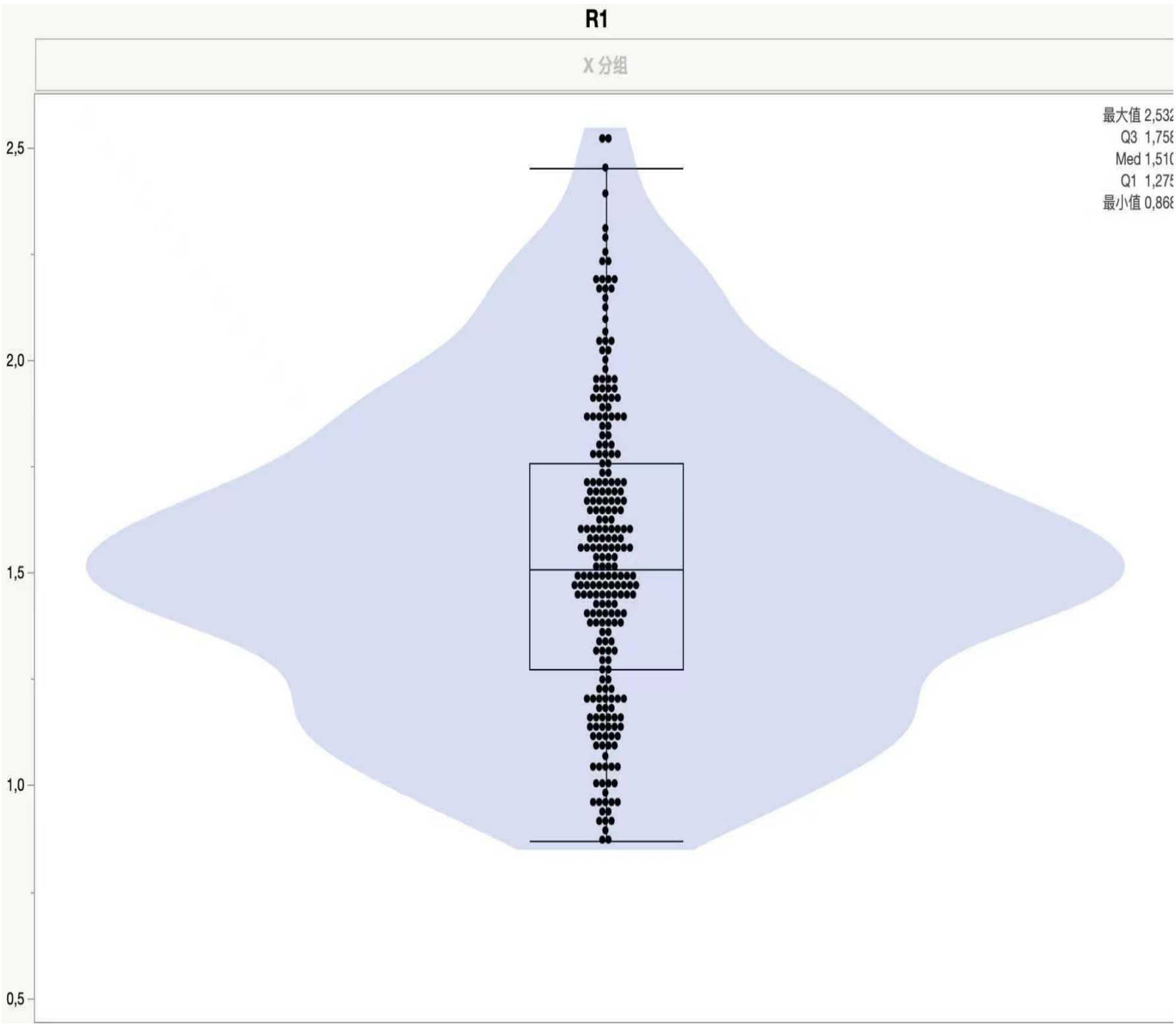
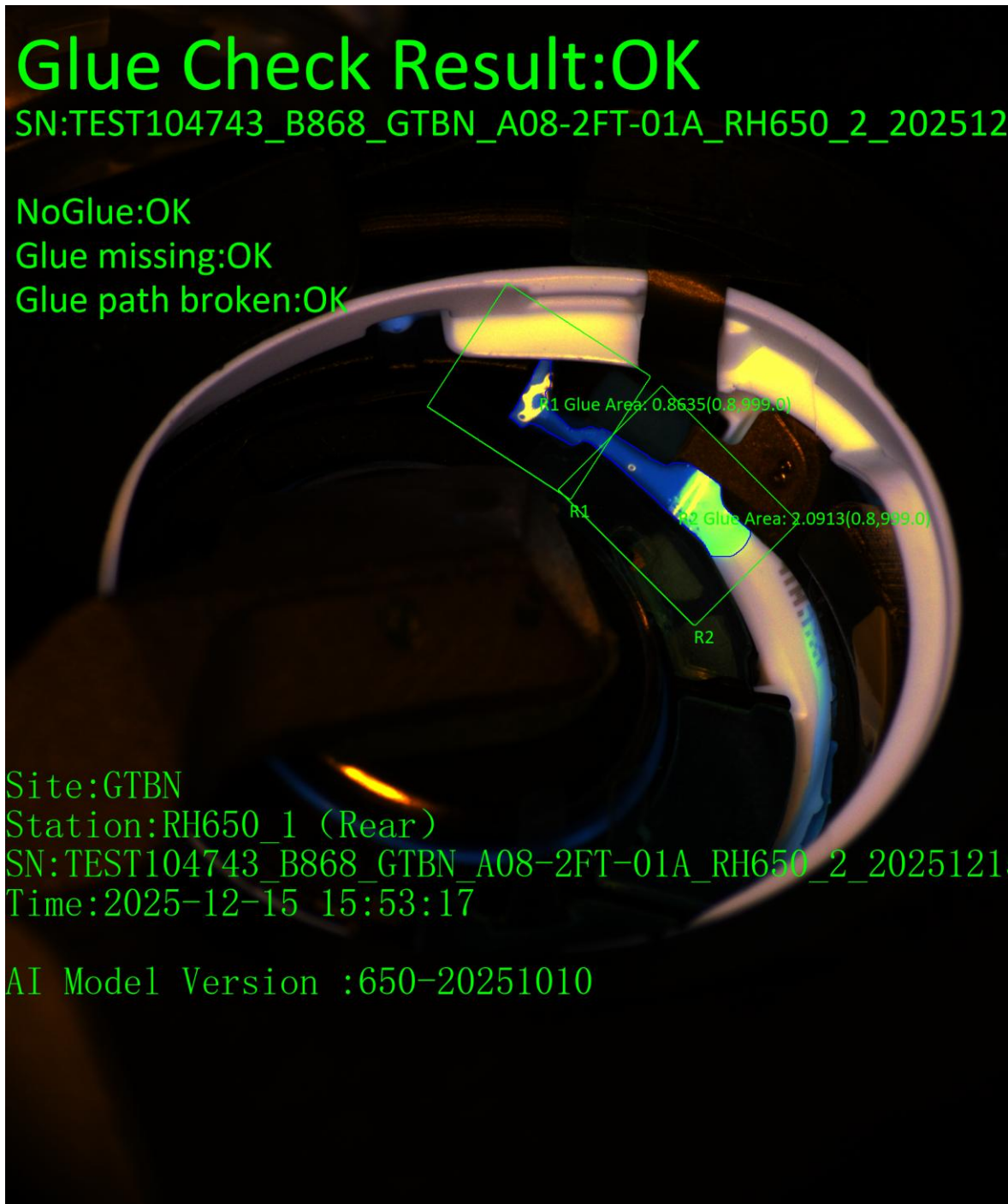


# H650 | Glue path AOI Product glue Inspection logic

Pose1\_Missing\_R1 MIN: 0.868

Pose1\_Missing\_R1 MAX: 2.5318

Pose1\_Missing\_R1 Data

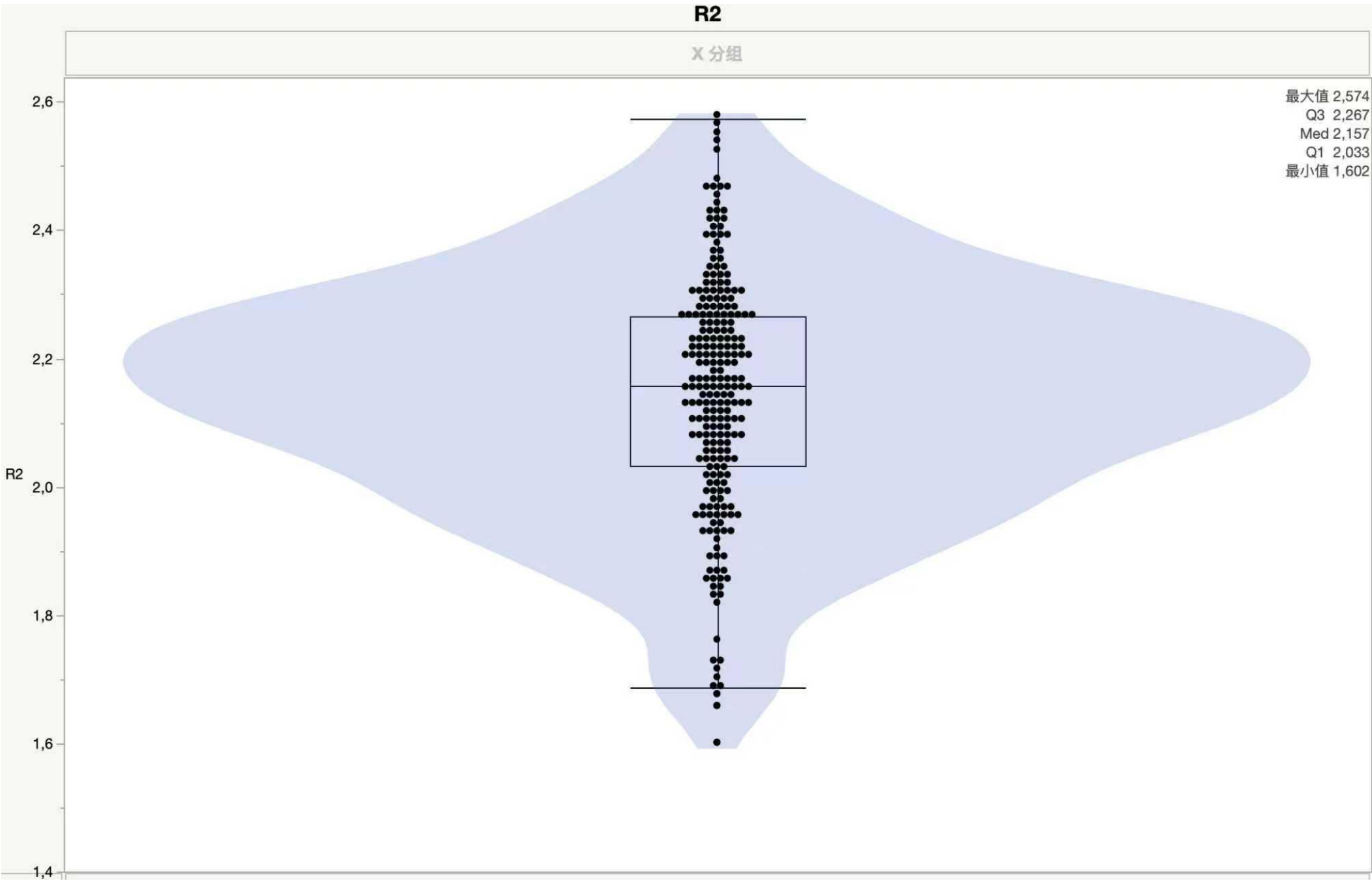
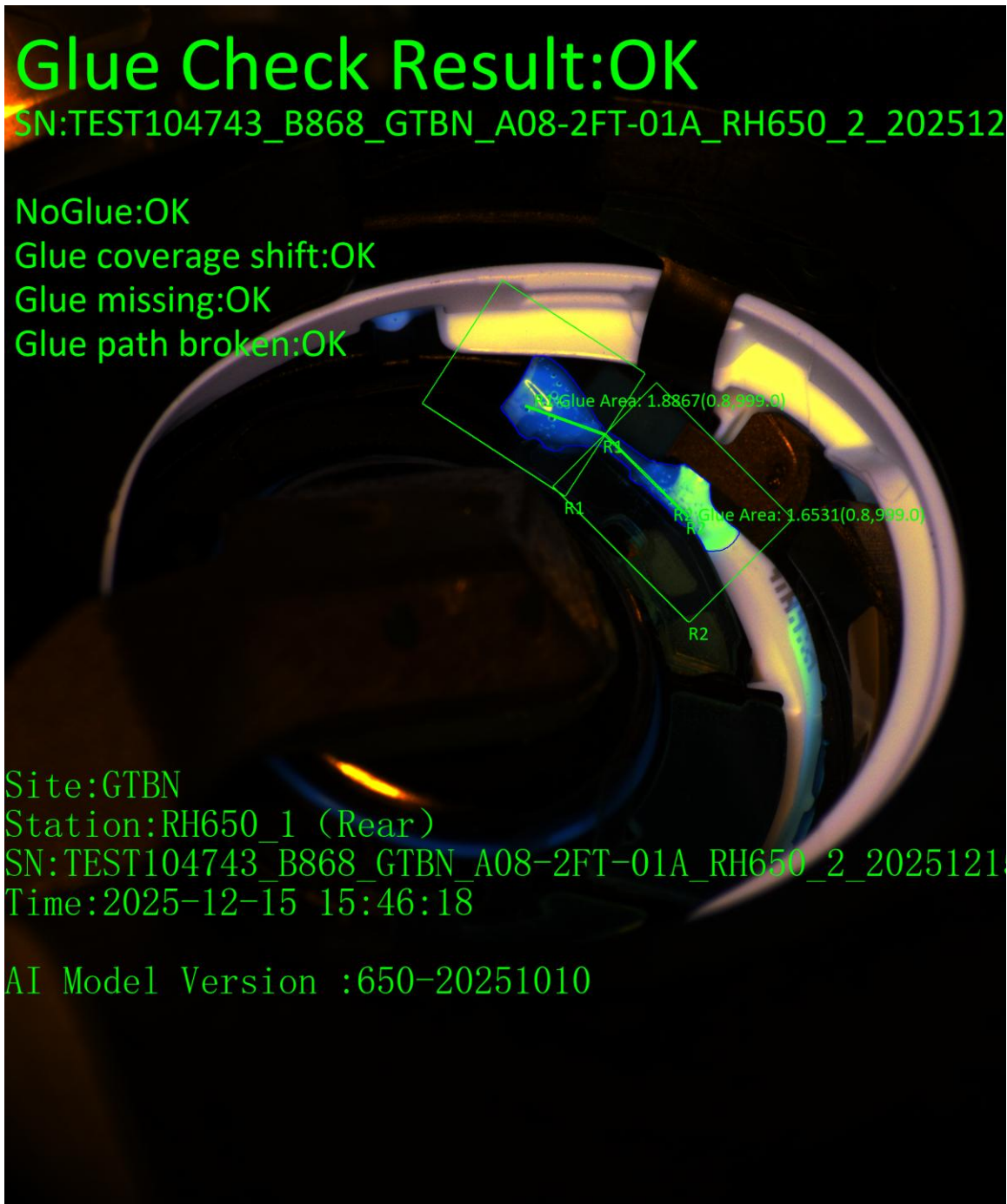


R1 Missing spec= Pose1\_Missing\_R1 MIN\*0.7=0.868\*0.7=0.6076

Pose1\_Missing\_R2 MIN: 1.602

Pose1\_Missing\_R2 MAX: 2.5742

Pose1\_Missing\_R2 Data



$R2 \text{ Missing spec} = \text{Pose1\_Missing\_R2 MIN} \times 0.7 = 1.602 \times 0.7 = 1.1214$